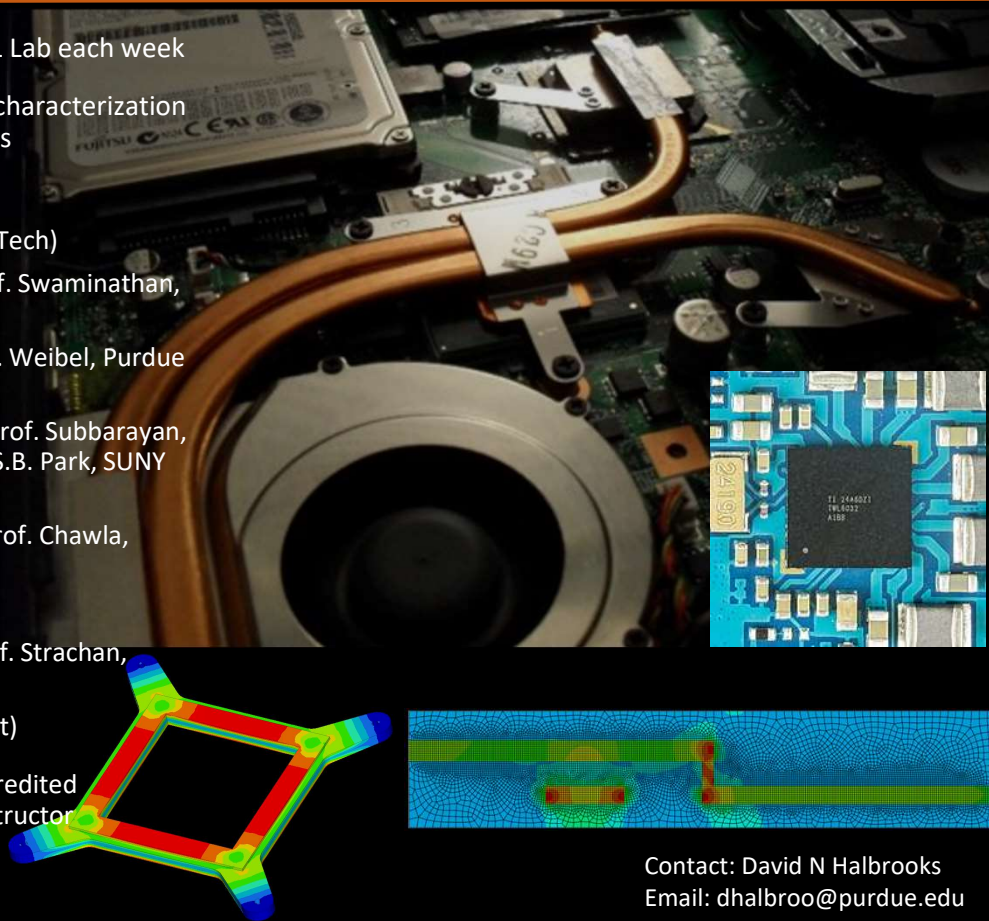


ME 597 ECE 595 MSE 597

Introduction to Electronics Packaging and Heterogeneous Integration

- Spring 2022, 3 Credits, Online Class, 2 Lectures+1 Lab each week
- Learn the basics of multi-disciplinary design and characterization of modern electronic components and assemblies
- Course Modules and Instructors:
 - Introduction (Prof. Swaminathan, Georgia Tech)
 - Electrical Design and Characterization (Prof. Swaminathan, Georgia Tech)
 - Thermal Design and Characterization (Prof. Weibel, Purdue and Prof. Schiffres, SUNY Binghamton)
 - Mechanical Design and Characterization (Prof. Subbarayan, Purdue, D.N. Halbrooks, Purdue and Prof. S.B. Park, SUNY Binghamton)
 - Material Selection and Characterization (Prof. Chawla, Purdue)
 - Package Fabrication (Prof. Bhate, ASU)
 - Statistical Modeling and Data Analysis (Prof. Strachan, Purdue)
 - Radiation Hardening (Prof. Alles, Vanderbilt)
- Prerequisites: Junior-level standing in an ABET accredited engineering curriculum or permission of course instructor



Contact: David N Halbrooks
Email: dhalbroo@purdue.edu